

## Multilayer Ceramic Chip Capacitors

## C3225JB1H106K250AB



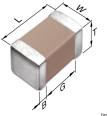






#### TDK item description C3225JB1H106KT\*\*\*\*

Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C3225 [EIA 1210]	
Status	Production	



imensions	in	mm

9	iize
Length(L)	3.20mm ±0.40mm
Width(W)	2.50mm ±0.30mm
Thickness(T)	2.50mm ±0.30mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	
Recommended Land Pattern (PA)	2.00mm to 2.40mm
Recommended Land Pattern (PB)	1.00mm to 1.20mm
Recommended Land Pattern (PC)	1.90mm to 2.50mm

Electrical Characteristics		
Capacitance	$10\mu F \pm 10\%$	
Rated Voltage	50VDC	
Temperature Characteristic	JB(±10%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	50ΜΩ	

Other	
Soldering Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	1000pcs

<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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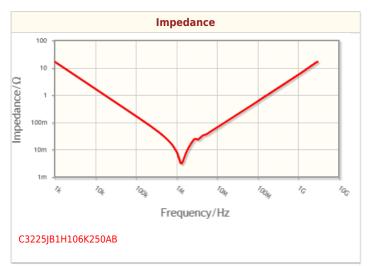


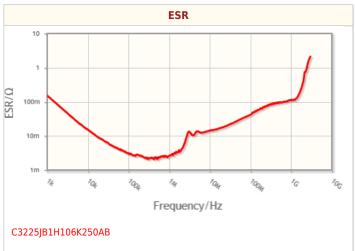


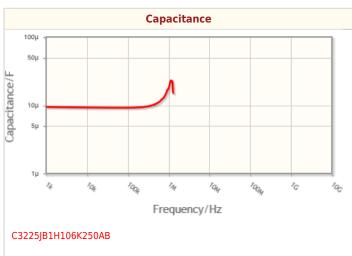




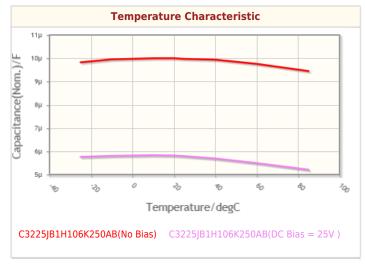
## Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

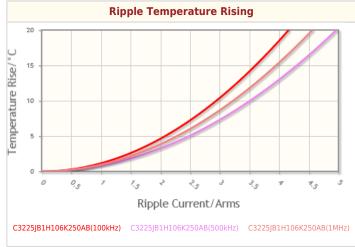












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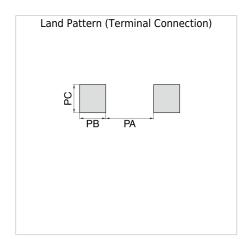








# **Associated Images**



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